



Feature Papers in 'Electrical, Electronics and Communications Engineering' Section

Guest Editors:

Dr. Graziella Scandurra

Department of Engineering,
University of Messina, 98166
Messina, Italy

Dr. Marco Carminati

Dipartimento di Elettronica,
Informazione e Bioingegneria
(DEIB), Politecnico di Milano,
20133 Milano, Italy

Prof. Dr. Nunzio Cennamo

Department of Engineering,
University of Campania Luigi
Vanvitelli, Via Roma 29, 81031
Aversa, Italy

Deadline for manuscript
submissions:

closed (31 December 2023)

Message from the Guest Editors

Electrical, electronics, and communications engineering are used in a large variety of application fields.

The main aim of this Special Issue is to bring together researchers active in the innovative developments of devices, schemes, instrumentation, materials and applications of systems exploiting electrical, electronics, and communications engineering.

Works addressing the wide aspects of this technology are sought, including, but not limited to, recent progresses in: novel devices and schemes with relative applications; dedicated instrumentation (hardware, applications and measurement methodologies); sensor, device and material characterization; smart systems.

A special emphasis of this Special Issue will be the current state-of-the-art and emerging trends.

Prospective authors are invited to submit feature papers on topics related to "*Electrical, Electronics and Communications Engineering*".





an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), Inspec, CAPlus / SciFinder, and other databases.

Journal Rank: JCR - Q2 (*Engineering, Multidisciplinary*) / CiteScore - Q1 (*General Engineering*)

Contact Us

Applied Sciences Editorial Office
MDPI, St. Alban-Anlage 66
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/applsci
applsci@mdpi.com
[X@Applsci](#)